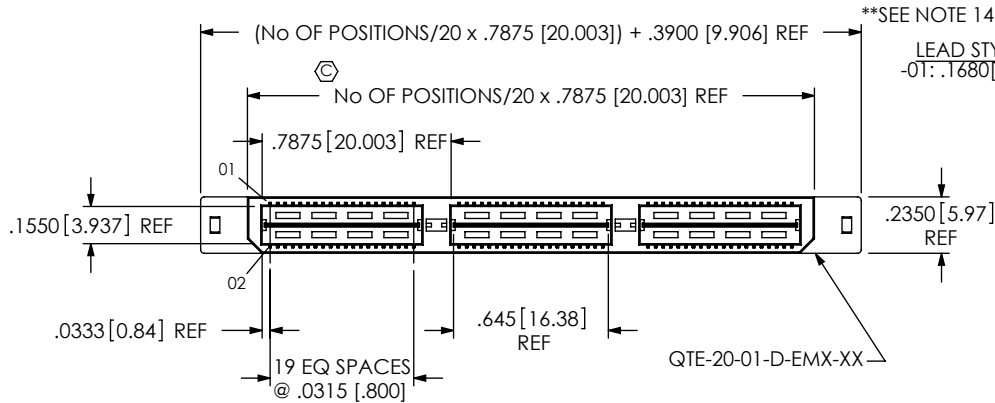


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THIS PRINT

TABLE 2					
EDGE MOUNT THICKNESS	"A"	"B"	"C"	BODY	CONTACT
-EM2	.130[3.30]	.0670[1.702]	.058[1.47]	QTE-20-01-D-EM2-XX	T-1S42-01-XXX
*-EM3	.160[4.06]	.0980[2.489]	.088[2.24]	QTE-20-01-D-EM3-XX	T-1S42-02-XXX

* = SEE NOTE 13

QTE-XXX-01-XXX-D-EMX-XX



No OF POSITIONS
-020, -040, -060,
**-080, **-100
(PER ROW)

**SEE NOTE 14

LEAD STYLE
-01: .1680[4.267]

OPTION

-GP: GUIDE POST
(USE QTE-20-01-D-EMX-XX-GP,
SEE FIG 2, SHEET 2)
-TY: TRAY PACKAGING

EDGE MOUNT THICKNESS

-EM2: .064[1.63] +/- .004 PCB
(USE QTE-20-01-D-EM2-XX & T-1S42-01-X)

-EM3:

(USE QTE-20-01-D-EM3-XX & T-1S42-02-X)
SEE NOTE 13

ROW SPECIFICATION

-D: DOUBLE (USE QTE-20-XX-D-EMX-XX)

PLATING SPECIFICATION

No OF BANKS

-F: 3μ" SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAILS
(USE T-1S42-XX-F & T-1G1-01-F) (SEE NOTE 11)

-L: 10μ" SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAILS
(USE T-1S42-XX-L & T-1G1-01-L)

-H: 30μ" GOLD IN CONTACT AREA, 3μ" GOLD ON TAIL
(USE T-1S42-XX-H & T-1G1-01-G)

-C: 50μ" GOLD IN CONTACT AREA, 3μ" GOLD ON TAIL
(USE T-1S42-XX-C & T-1G1-01-L)

-STL: 30μ" SELECTIVE GOLD IN CONTACT AREA, TIN/LEAD (90%/10 +/-5%) TAIL
(USE T-1S42-XX-STL & T-1G1-01-STL)

-FTL: 3μ" SELECTIVE GOLD IN CONTACT AREA, TIN/LEAD (90%/10 +/-5%) TAIL
(USE T-1S42-XX-FTL & T-1G1-01-FTL)

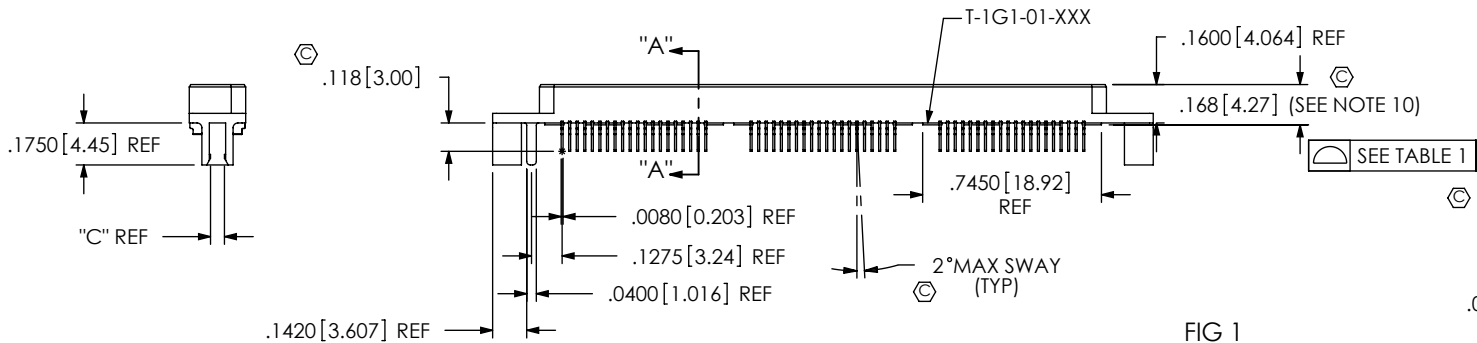
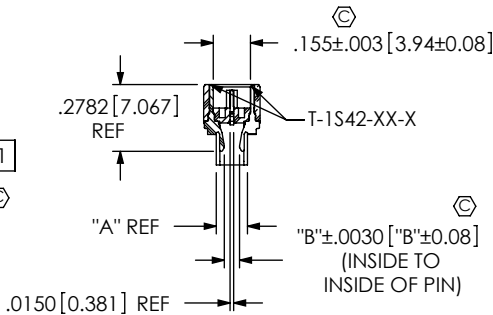


FIG 1
QTE-060-01-XXX-D-EM2 SHOWN



SECTION "A"- "A"

NOTES:

1. Ⓢ REPRESENTS A CRITICAL DIMENSION.
2. NOTE DELETED.
3. BURR ALLOWANCE: .0015 [.03] MAX.
4. MINIMUM TERMINAL RETENTION: 6 OZ.
5. MINIMUM GROUND PLANE RETENTION: 1 LB.
6. PARTS TO BE MOLD-TO-POSITION.
7. NOTE DELETED.
8. NOTE DELETED.
9. NOTE DELETED.
10. MAX VARIANCE: .002 [.05].
11. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING.
12. SEE http://www.samtec.com/processing/edgemt_tectalk/index.htm FOR INFORMATION ON PROCESSING EDGE MOUNT PARTS TO BOARDS.
13. -EM3 IS NOT A STANDARD OFFERING; AVAILABLE AS AN ASP ONLY. PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP WITH ORDER INQUIRIES
14. FOR NEW APPLICATIONS REQUIRING THESE POSITIONS, PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP.
15. PARTS WITHOUT -TY OPTION SHALL BE PACKAGED IN TRAYS.

TABLE 1		
No OF POSITIONS	GND PLANE COPLANARITY	ASSEMBLY BOW
-020 THRU -060	.004 [.10]	.004 [.10]
-080 THRU -100	.005[1.27]	.005[1.27]

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN INCHES.

TOLERANCES ARE:

DECIMALS

ANGLES

.XX: ±.01 [.3]

2°

.XXX: ±.005 [.13]

.XXXX: ±.0020 [.051]

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MATERIAL:

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SHEET SCALE: 1:0.8

INSULATOR: LCP COLOR: BLACK
TERMINAL & GROUND PLANE: PHOS BRONZE

DESCRIPTION:

.8mm EDMOUNT HS TERMINAL ASSEMBLY

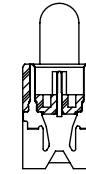
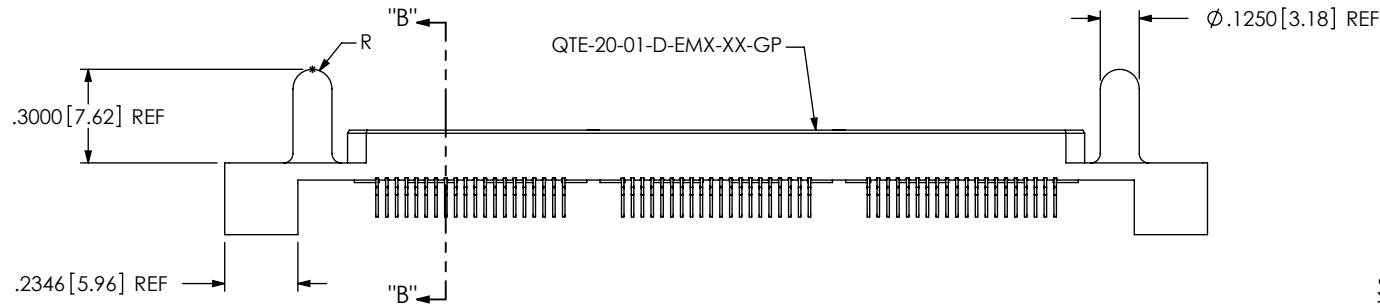
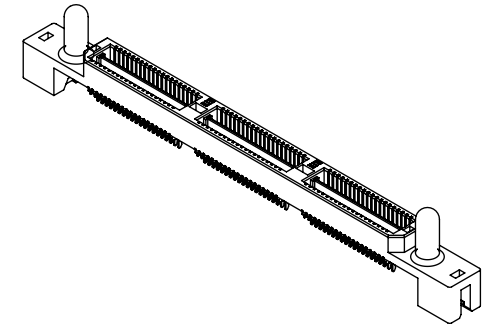
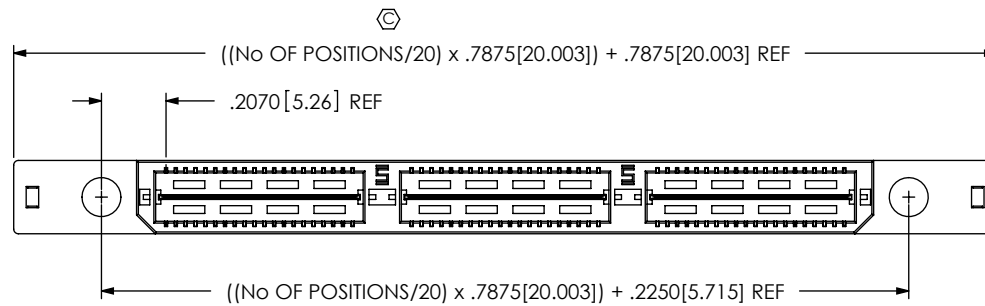
DWG. NO.

QTE-XXX-01-XXX-D-EMX-XX

BY: DEAN P

9/2/1999

SHEET 1 OF 2



SECTION "B"-"B"

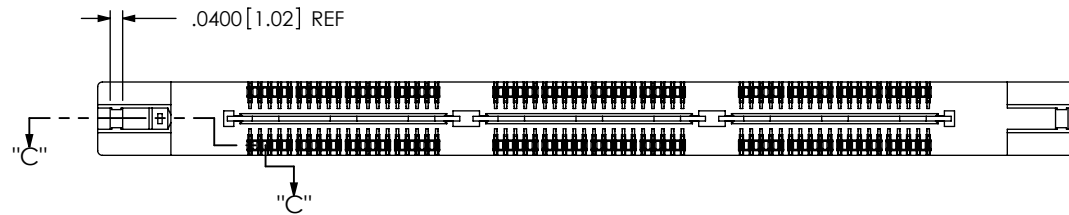
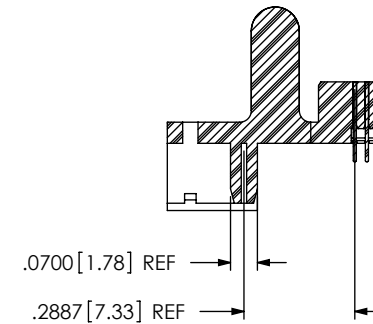


FIG 2
-GP OPTION
(SAME AS FIG 1, UNLESS OTHERWISE STATED)



SECTION "C"-"C"
SCALE 2 : 1

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SHEET SCALE: 1.625:1

samtec

520 PARK EAST BLVD, NEW ALBANY, IN 47150
PHONE: 812-944-6733 FAX: 812-948-5047
e-Mail: info@SAMTEC.com code: 55322

DESCRIPTION:
.8mm EDGEMOUNT HS TERMINAL ASSEMBLY

DWG. NO.
QTE-XXX-01-XXX-D-EMX-XX

BY: DEAN P 9/2/1999 SHEET 2 OF 2